### Drill Chart: Top to Bottom

All units are in millimeters.

<table>
<thead>
<tr>
<th>Figure</th>
<th>Size</th>
<th>Plated</th>
<th>QTY</th>
</tr>
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<tbody>
<tr>
<td></td>
<td>0.3</td>
<td>Plated</td>
<td>776</td>
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<tr>
<td></td>
<td>1.0</td>
<td>Non-plated</td>
<td>2</td>
</tr>
<tr>
<td></td>
<td>1.0</td>
<td>Non-plated</td>
<td>1</td>
</tr>
<tr>
<td></td>
<td>2.5</td>
<td>Non-plated</td>
<td>6</td>
</tr>
<tr>
<td></td>
<td>2.3x1.75</td>
<td>Non-plated</td>
<td>4</td>
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All drawings seen from Layer 1 (Top) unless otherwise stated.

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**Dynamic Precision**

<table>
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<tr>
<th>Title</th>
<th>Layer</th>
<th>PCB No.</th>
<th>Revision</th>
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<tr>
<td>ZLLRC</td>
<td>DRM</td>
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</table>

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Latest modification date

**03 April 2013**

Size: A4
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